**KEY FACTS**

**Pre-molded, routable, fine pitch leadframe**
- Allows for complex designs where QFN cannot
- Smaller package footprint with thinner height

**Cost competitive vs. FBGA/LGA**
- Lower materials and via formation costs

**Increased Package Performance**
- Better electrical with shorter wire lengths
- Better grounding options
- Better thermal path compared to FBGA/LGA

**MIS MARKET DRIVERS**

**QFN Package Limitations**
- Pitch and routing limits
- Limited grounding options
- Package size and thickness

**FBGA/LGA Package Limitations**
- High material and via formation costs
- Not able to meet MSL Level 1

**Alternative to FOWLP**
- Interposer for fine pitch micro-bump Flip Chip fan-out

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**MIS lead frame is pre-molded**

**MIS lead frame has a fine pitch**

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